Final Product Change Notification

201408014F01

Issue Date: 08-Nov-2014
Effective Date: 20-Feb-2015

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For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT23

Details of this Change

Scheduled changes affect product types in SOT23 package only. This FPCN is the follow-up of the APCN 201408014A issued on 11-Sep-2014.

(1) The bond wire material will be changed from gold (Au) to copper (Cu). Implementation of changes to copper wire as given by implementation date below. Gold wire remains qualified for supply security reasons only.
(2) A second source mold compound supplier will be introduced for copper wire products.

Old product: Wire material is Au (with currently used mold compound suppliers)
Changed product: Wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers)

The design and materials of all other components will remain unchanged: Die, die attach and lead frame. Reliability qualification and full electrical characterization over temperature has been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
(2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM for associated types in SOT23 package. The second source supplier is already well established for NXP GA discrete semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 10-Dec-2014.

Production

Planned first shipment 16-Feb-2015

Impact

No impact to the products' functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201408014A	11-Sep-2014		Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT23

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 08-Dec-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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